## **EUROPEAN PATENT OFFICE**

## **Patent Abstracts of Japan**

**PUBLICATION NUMBER** 

61244057

**PUBLICATION DATE** 

30-10-86

APPLICATION DATE

22-04-85

APPLICATION NUMBER

60088433

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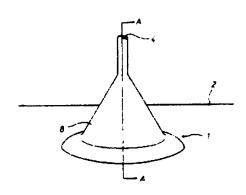
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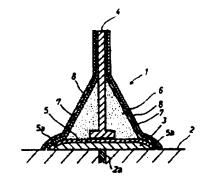
TITLE

: TERMINAL CONNECTION

STRUCTURE AND ITS CONNECTING

METHOD





ABSTRACT :

PURPOSE: To prevent abnormal operation of IC package or the like, by making all peripheral part on a lead connection part to be exposed from a soldering material and covering all the peripheral part on the lead connection part with nickel layers which cover all the surface of the soldering material, to prevent migration.

CONSTITUTION: A lead connection part 3 is composed of a metallized layer on which paste such as tungsten is printed and burned, and a nickel layer 5 is piled above it by electrolytic plating. The lead connection part 3 is connected to a conducting part 2a which is connected by internal wiring of a substrate 2. A terminal 4 is fixed on the nickel layer 5 by silver solder 6, so as not to make the silver solder 6 to cover the peripheral part 5a of the nickel layer 5. The terminal 4, the silver solder 6, and the peripheral part 5a of the nickel layer 5 are covered with another nickel layer 7, and above it, a gold layer 8 is electroplated by a solution of gold cyanide for being oxidization-proof and chemicals-proof. Hence, because the silver solder 6 does not made cover the peripheral part 5a of the nickel layer 5 on the lead connection part 3 and two nickel layers 5 and 7 are completely connected at the peripheral part 5a, the silver solder 6 can be prevented from migrating.

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